

Abstract

An edge exposure device and method. The wafer edge exposure device comprises: a machine frame (1); edge exposure units (2) installed on the machine frame (1) and used to expose an edge of a wafer; pre-alignment units (3) used to align a center of the wafer, fix a position of the wafer, and operate together with the edge exposure units (2) to complete an edge exposure operation; a wafer storage unit (4) used to store and test the wafer; a robotic arm (5) used to move the wafer; and a main control unit (6) used to control all the operation units in the wafer edge exposure device. The edge exposure units (2) and the pre-alignment units (3) share an operation platform, providing a compact structure. Two sets of the edge exposure units (2) and the pre-alignment units (3) are respectively arranged, resulting in high production efficiency.